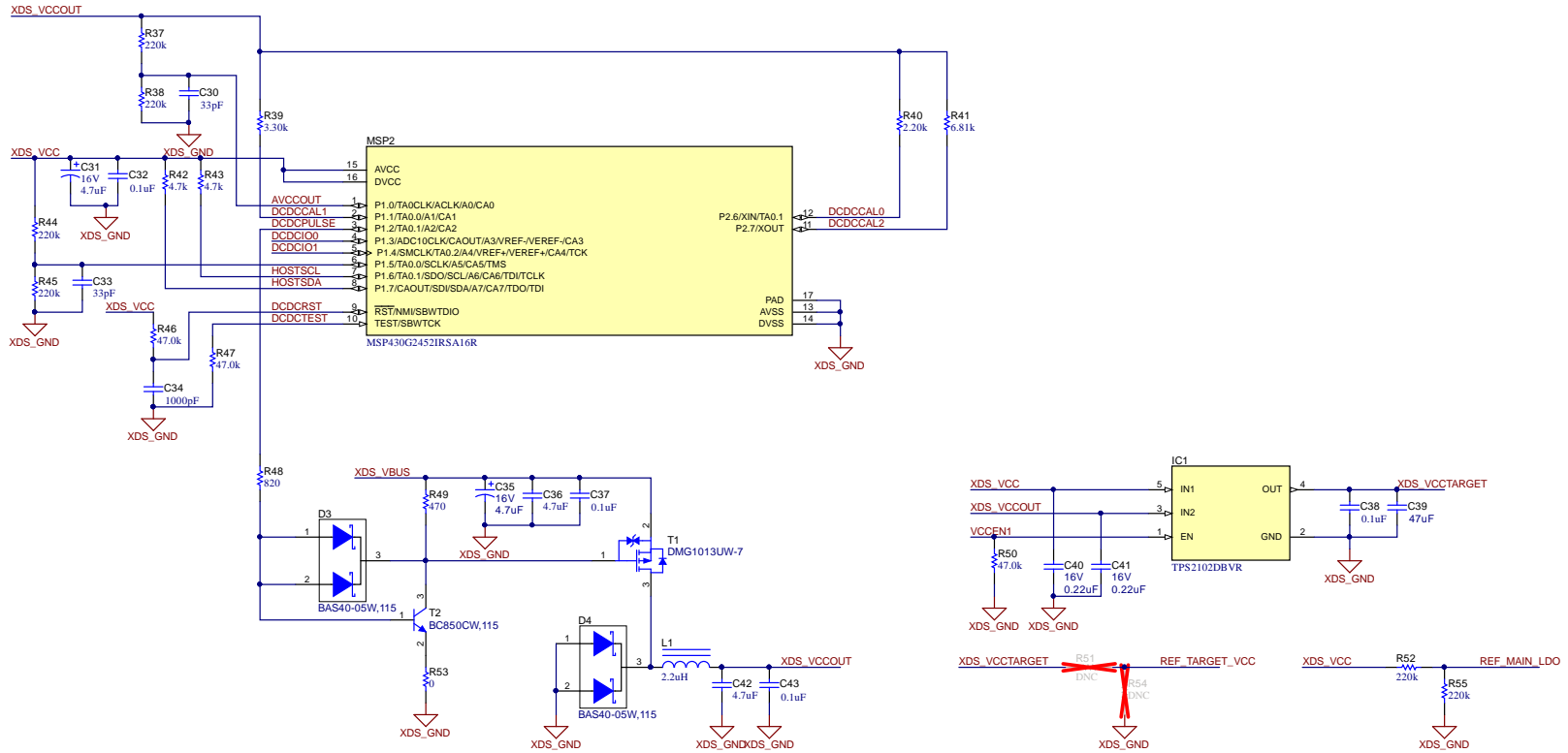


Software-controlled DCDC converter

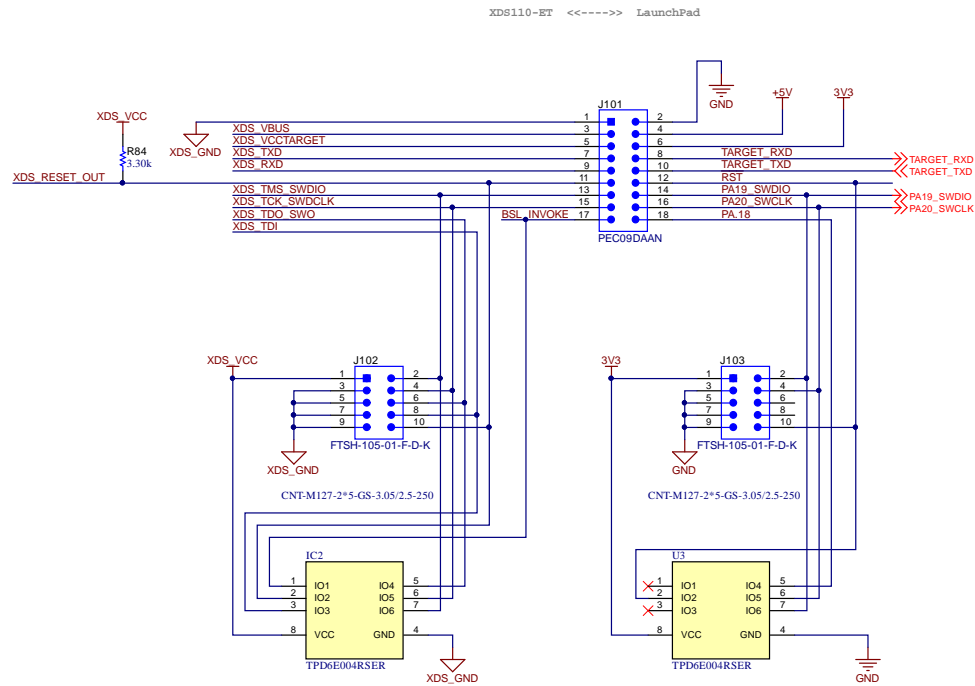
Energy measurement method protected under U.S. Patent Application 13/329,073 and subsequent patent applications



Orderable: LP-MSPMOL1306	Designed for: Public Release	Mod. Date: 11/25/2021
TID #: N/A	Project Title: LP-MSPMOL1306	
Number: MCU099	Rev: 1.0	Sheet Title: XDS110-ET EnergyTrace
Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 3 of 6
Drawn By: Luke Ledbetter	File: MCU099_03_XDS110-ET_EnergyTrace_Sch.Dwg	Size: B
Engineer: Eddie LaCosta	Contact: http://www.ti.com/support	



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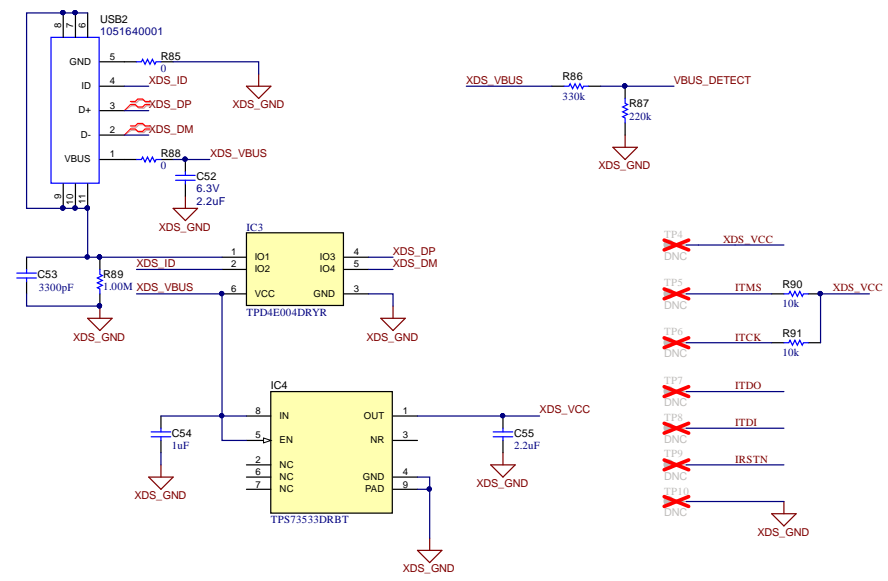


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TID #: N/A	Project Title: LP-MSPM0L1306	
Number: MCU099	Rev: 1.0	Sheet Title: XDS110-ET Interface
Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 4 of 6
Drawn By: Luke Ledbetter	File: MCU099_04_XDS110_Target_Interface_Sch.Dwg	Size: B
Engineer: Eddie LaCost	Contact: http://www.ti.com/support	

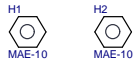


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TID #: N/A	Project Title: LP-MSPMOL1306	
Number: MCU099	Rev: 1.0	Sheet Title: XDS110-ET USB Power
Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 5 of 6
Drawn By: Luke Ledbetter	File: MCU099_05_XDS110-ET_USB_Power.SchDoc	Size: B
Engineer: Eddie LaCost	Contact: http://www.ti.com/support	

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PCB Number: MCU099
PCB Rev: 1.0
Printed Circuit Board



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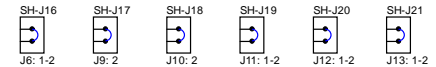
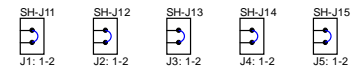
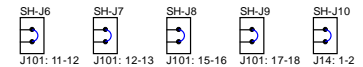
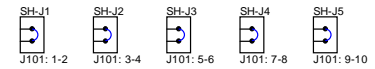
Logo3
PCB
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Logo4
PCB
LOGO
ESD Susceptible

Logo6
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FCC disclaimer

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PCB
LOGO
WEEE logo



USB1
MECH
AK67421-0.3

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4
Assembly Note
Place a click-in Standoff (MAE-10, KangYang) in hole MH1/MH2

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TID #:	N/A	Project Title:	LP-MSPM0L1306	
Number:	MCU099	Rev:	1.0	
Sheet Title:	Hardware	Sheet:	6 of 6	
Assembly Variant:	Variant 1	File:	MCU099_06 Hardware_SchDoc	
Drawn By:	Luke Ledbetter	Size:	B	
Engineer:	Eddie LaCost	Contact:	http://www.ti.com/support	



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